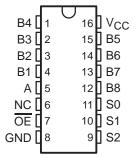
SCDS019G - MAY 1995 - REVISED MAY 1998

- Functionally Equivalent to QS3251
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

The SN74CBT3251 is a 1-of-8 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

D, DB, DBQ, DGV, OR PW PACKAGE (TOP VIEW)



NC - No internal connection

When output enable (\overline{OE}) is low, the SN74CBT3251 is enabled. S0, S1, and S2 select one of the B outputs for the A-input data.

The SN74CBT3251 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each multiplexer)

	INPUTS			FUNCTION
OE	S2	S1	S0	FUNCTION
L	L	L	L	A port = B1 port
L	L	L	Н	A port = B2 port
L	L	Н	L	A port = B3 port
L	L	Н	Н	A port = B4 port
L	Н	L	L	A port = B5 port
L	Н	L	Н	A port = B6 port
L	Н	Н	L	A port = B7 port
L	Н	Н	Н	A port = B8 port
Н	Χ	Χ	Χ	Disconnect

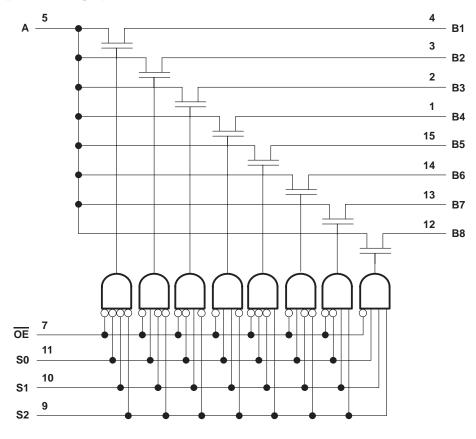


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SCDS019G - MAY 1995 - REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, $I_K (V_{I/O} < 0)$	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package 113°C/W
	DB package
	DBQ package
	DGV package 180°C/W
	PW package 149°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



SCDS019G - MAY 1995 - REVISED MAY 1998

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
II		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ
Icc		$V_{CC} = 5.5 \text{ V},$	$I_{O} = 0$,	$V_I = V_{CC}$ or GND			3	μΑ
∆l _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
C _i	Control inputs	$V_I = 3 V \text{ or } 0$				3.5		pF
C _{io(OFF)}	A port)/ 0.\/ = = 0				17.5		pF
	B port	$V_{O} = 3 \text{ V or } 0,$	OE = V _{CC}			4		ρŀ
r _{on} §		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		14	20	
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA		5	7	Ω
				I _I = 30 mA		5	7	
			V _I = 2.4 V,	I _I = 15 mA		10	15	

[†] All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V	V _{CC} = 5 V ± 0.5 V		UNIT
			MIN MAX	MIN	MAX	
$t_{pd}\P$	A or B	B or A	0.35		0.25	ns
^t pd	S	А	6	2	5.5	ns
4	S	В	6.4	1.5	5.6	ns
t _{en}	ŌĒ	A or B	6.4	1.6	5.8	
^t dis	S	В	6.8	1.9	6.4	20
	ŌĒ	A or B	6	2.3	6.2	ns

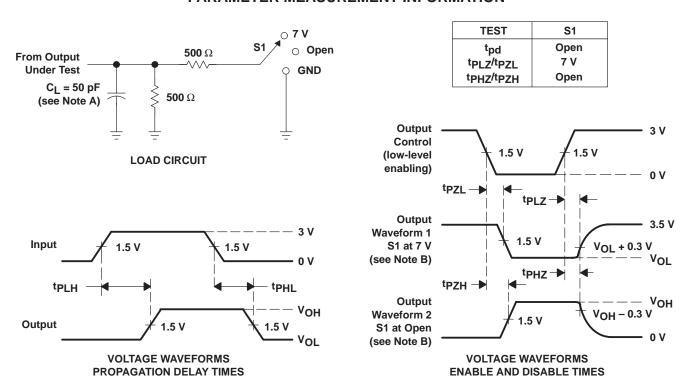
The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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